PRINTED WIRING BOARD AND ITS MANUFACTURE

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Abstract of **JP 10126038 (A)**

PROBLEM TO BE SOLVED: To make an exposing process and developing process using a photomask omittable after a resist is formed by roughening the surface of a metallic layer on a wiring circuit forming surface side so that a prescribed roughness can be obtained non-directionally and jetting photo-setting ink upon a roughened circuit forming section from an ink jet head. SOLUTION: The surface of a metallic layer 11 is roughened by non- directionally forming recessed and projecting sections by spraying particles with a sandblaster 16 from the direction perpendicular to the surface in a roughening process. After the surface is roughened, photo-setting ink is jetted upon the roughened surface from an ink jet head 17 in accordance with a set pattern.; Consequently, the cured photo-curing ink composition 13B corresponding to a circuit forming section 13a is formed on the surface of the roughened metal layer 11. Thereafter, a conductive circuit 11A can be formed on an insulating layer 12 through an etching process. The sandblast in the roughening process is performed by using, for example, fused alumina particles having a particle size of #220.